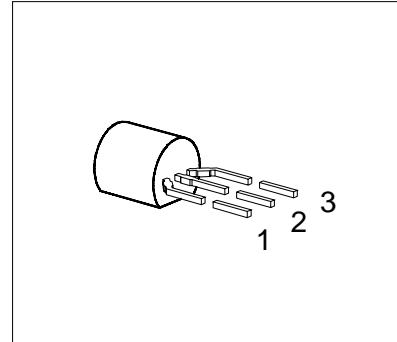


SIPMOS® Small-Signal Transistor

- V_{DS} 250 V
- I_D 0.07 A
- $R_{DS(on)}$ 100 Ω
- N channel
- Depletion mode
- High dynamic resistance
- Available grouped in $V_{GS(th)}$



Type	Ordering Code	Tape and Reel Information	Pin Configuration			Marking	Package
			1	2	3		
BSS 229	Q62702-S600	E6296: 1500 pcs/reel; 2 reels/carton; source first	G	D	S	SS229	TO-92

Maximum Ratings

Parameter	Symbol	Values	Unit
Drain-source voltage	V_{DS}	250	V
Drain-gate voltage, $R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	250	
Gate-source voltage	V_{GS}	± 20	
ESD Sensitivity (HBM) as per MIL-STD 883	–	Class 1	
Continuous drain current, $T_A = 25^\circ\text{C}$	I_D	0.07	A
Pulsed drain current, $T_A = 25^\circ\text{C}$	$I_{D\text{ puls}}$	0.21	
Max. power dissipation, $T_A = 25^\circ\text{C}$	P_{tot}	0.63	W
Operating and storage temperature range	T_j, T_{stg}	– 55 ... + 150	°C

Thermal resistance, chip-ambient (without heat sink)	R_{thJA}	≤ 200	K/W
DIN humidity category, DIN 40 040	–	E	–
IEC climatic category, DIN IEC 68-1	–	55/150/56	

Electrical Characteristics

at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static Characteristics

Drain-source breakdown voltage $V_{GS} = -3\text{ V}$, $I_D = 0.25\text{ mA}$	$V_{(\text{BR})\text{DSS}}$	250	—	—	V
Gate threshold voltage $V_{DS} = 3\text{ V}$, $I_D = 1\text{ mA}$	$V_{GS(\text{th})}$	— 1.8	— 1.4	— 0.7	
Drain-source cutoff current $V_{DS} = 250\text{ V}$, $V_{GS} = -3\text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{DSS}	— —	— —	100 200	nA μA
Gate-source leakage current $V_{GS} = 20\text{ V}$, $V_{DS} = 0$	I_{GSS}	—	10	100	nA
Drain-source on-resistance $V_{GS} = 0\text{ V}$, $I_D = 0.014\text{ A}$	$R_{DS(\text{on})}$	—	75	100	Ω

Dynamic Characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}$, $I_D = 0.07\text{ A}$	g_{fs}	0.05	0.10	—	S
Input capacitance $V_{GS} = 0$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{iss}	—	85	120	pF
Output capacitance $V_{GS} = 0$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{oss}	—	6	10	
Reverse transfer capacitance $V_{GS} = 0$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{rss}	—	2	3	
Turn-on time t_{on} , ($t_{\text{on}} = t_{d(\text{on})} + t_r$) $V_{DD} = 30\text{ V}$, $V_{GS} = -2\text{ V} \dots + 5\text{ V}$, $R_{GS} = 50\text{ Ω}$, $I_D = 0.15\text{ A}$	$t_{d(\text{on})}$ t_r	— —	4 10	6 15	ns
Turn-off time t_{off} , ($t_{\text{off}} = t_{d(\text{off})} + t_f$) $V_{DD} = 30\text{ V}$, $V_{GS} = -2\text{ V} \dots + 5\text{ V}$, $R_{GS} = 50\text{ Ω}$, $I_D = 0.15\text{ A}$	$t_{d(\text{off})}$ t_f	— —	10 15	13 20	

Electrical Characteristics (cont'd)

at $T_j = 25^\circ\text{C}$, unless otherwise specified.

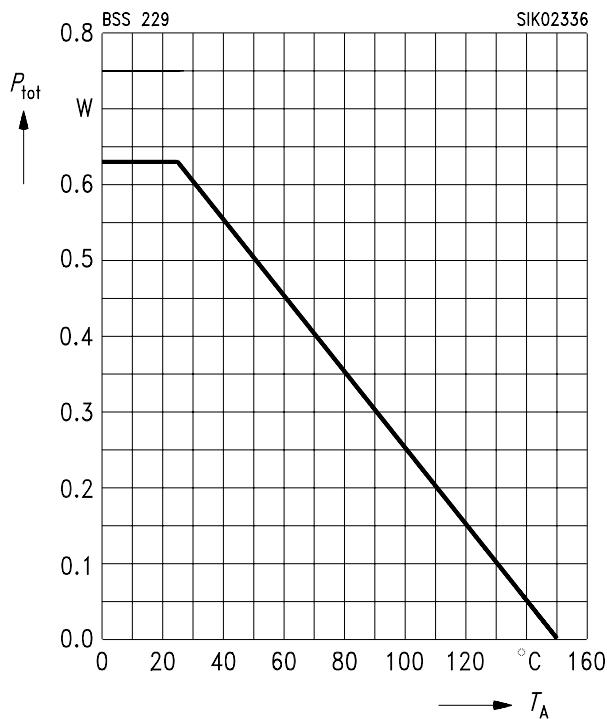
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Continuous reverse drain current $T_A = 25^\circ\text{C}$	I_S	—	—	0.07	A
Pulsed reverse drain current $T_A = 25^\circ\text{C}$	I_{SM}	—	—	0.21	
Diode forward on-voltage $I_F = 0.14 \text{ A}, V_{GS} = 0$	V_{SD}	—	0.8	1.2	V

$V_{GS(\text{th})}$ Grouping	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Range of $V_{GS(\text{th})}$	$\Delta V_{GS(\text{th})}$	—	0.15	V	—
Threshold voltage selected in groups: ¹⁾	$V_{GS(\text{th})}$				$V_{DS1} = 0.2 \text{ V};$ $V_{DS2} = 3 \text{ V};$ $I_D = 10 \mu\text{A}$
F		— 1.535	— 1.385	V	
G		— 1.635	— 1.485	V	
A		— 1.735	— 1.585	V	
B		— 1.835	— 1.685	V	
C		— 1.935	— 1.785	V	
D		— 2.035	— 1.885	V	

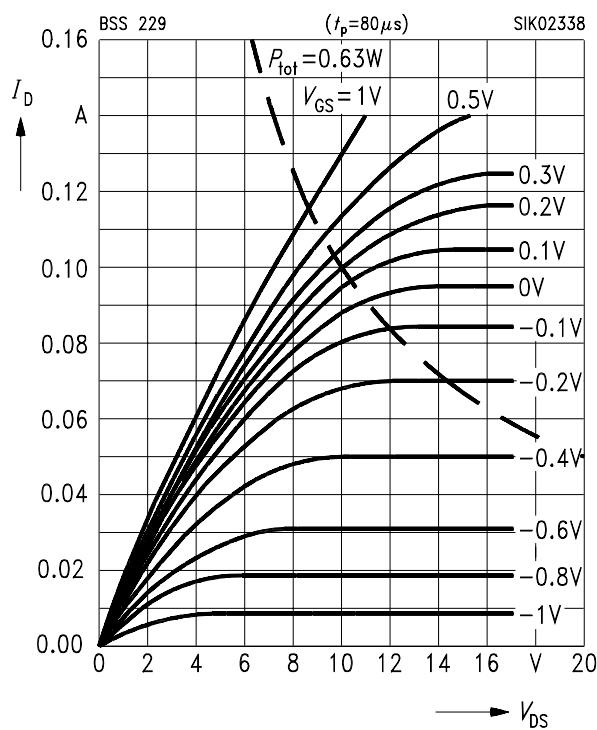
- 1) A specific group cannot be ordered separately.
Each reel only contains transistors from one group.

Characteristics
at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Total power dissipation $P_{\text{tot}} = f(T_A)$

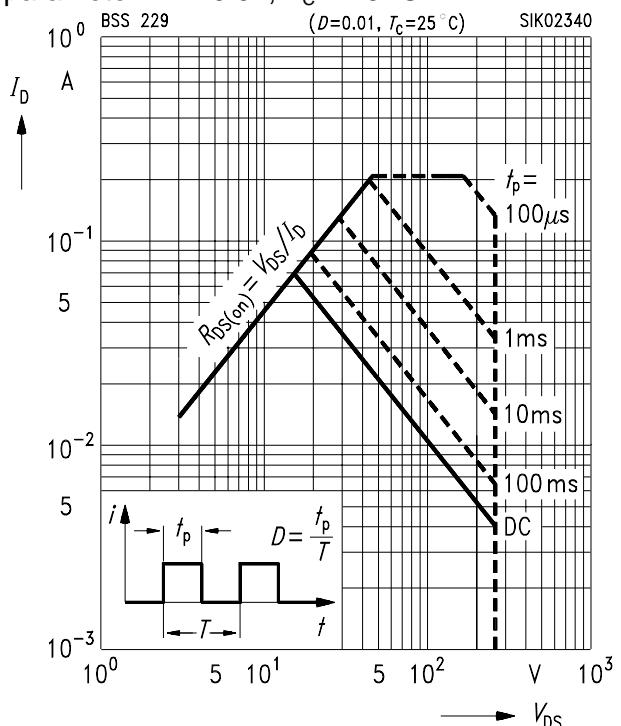


Typ. output characteristics $I_D = f(V_{DS})$
parameter: $t_p = 80 \mu\text{s}$



Safe operating area $I_D = f(V_{DS})$

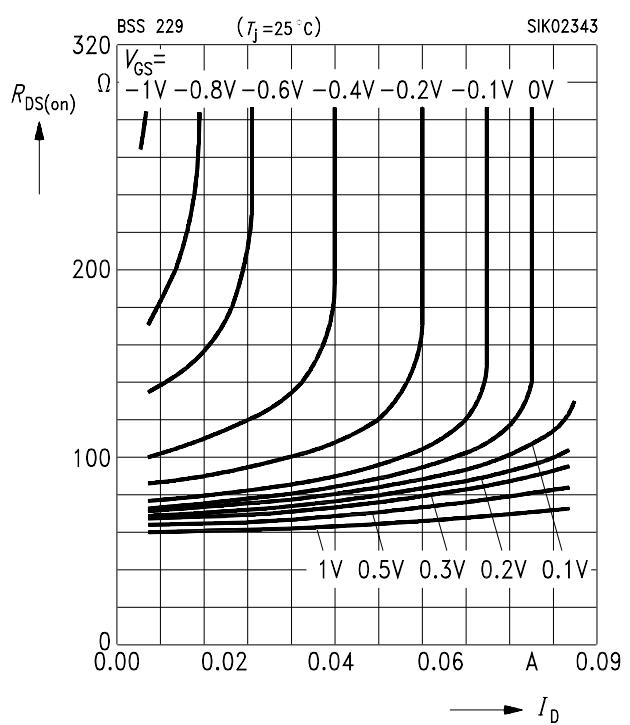
parameter: $D = 0.01, T_c = 25^\circ\text{C}$



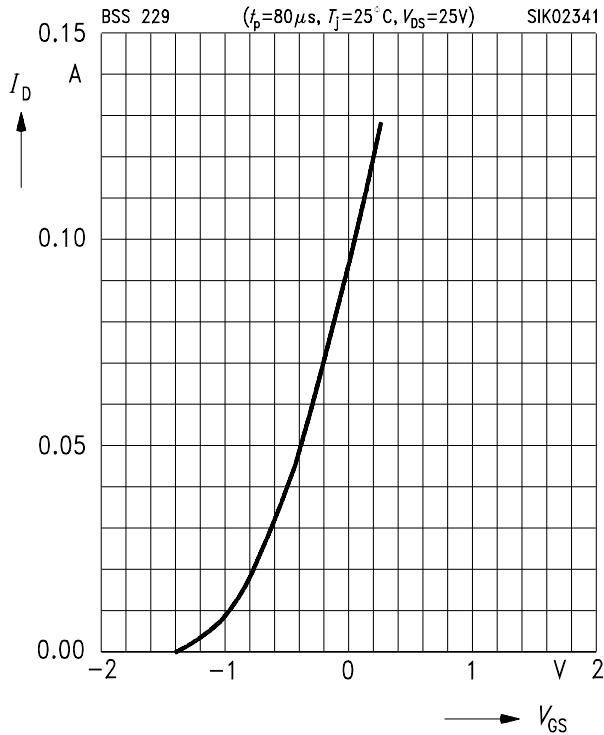
Typ. drain-source on-resistance

$R_{DS(\text{on})} = f(I_D)$

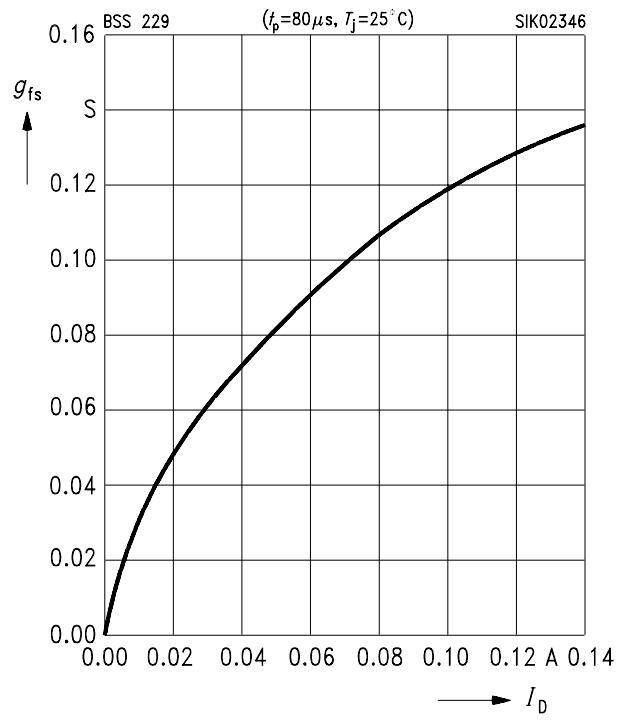
parameter: V_{GS}



Typ. transfer characteristics $I_D = f(V_{GS})$
 parameter: $t_p = 80 \mu s$, $V_{DS} \geq 2 \times I_D \times R_{DS(on)max.}$

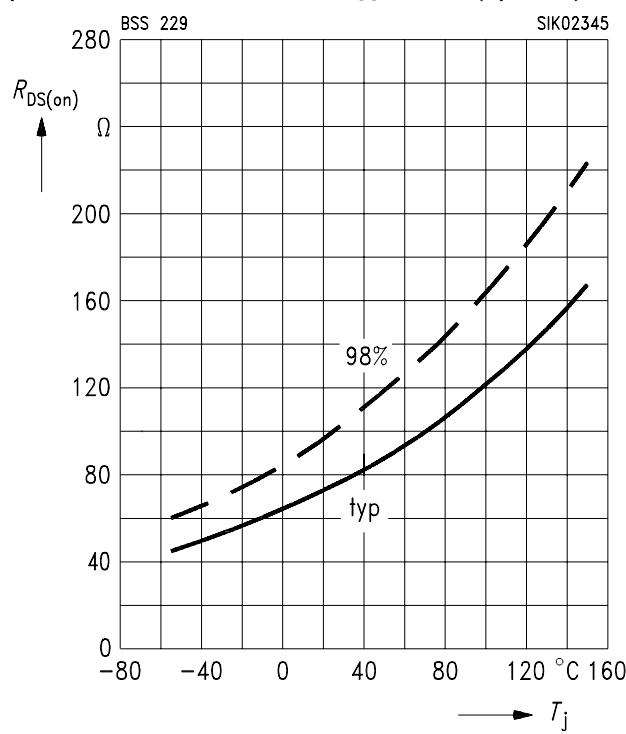


Typ. forward transconductance $g_{fs} = f(I_D)$
 parameter: $V_{DS} \geq 2 \times I_D \times R_{DS(on)max.}$, $t_p = 80 \mu s$

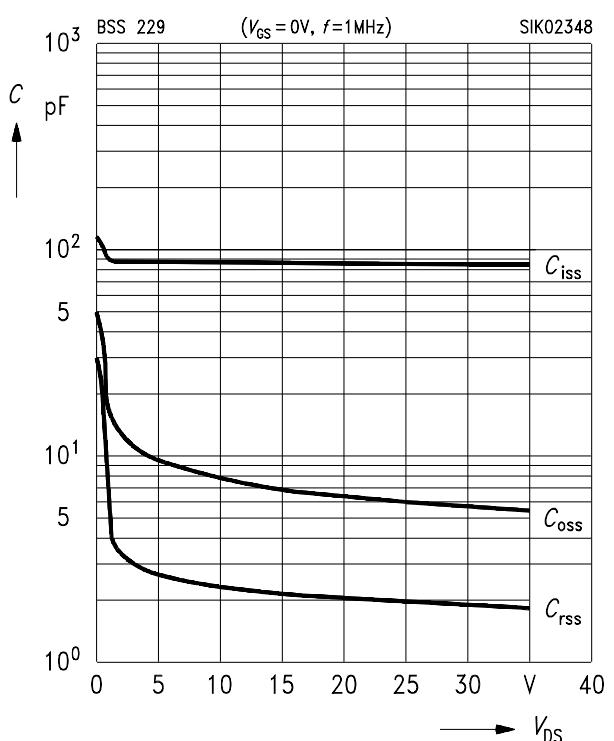


Drain-source on-resistance

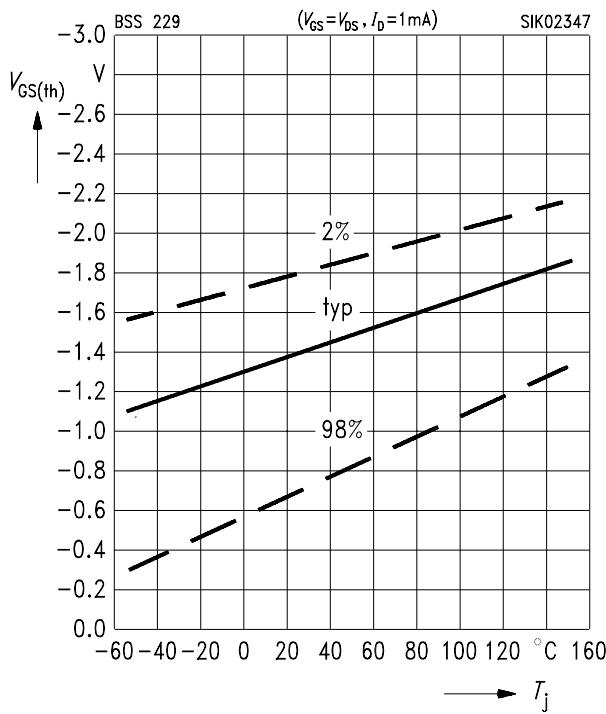
$R_{DS(on)} = f(T_j)$
 parameter: $I_D = 0.014$ A, $V_{GS} = 0$ V, (spread)



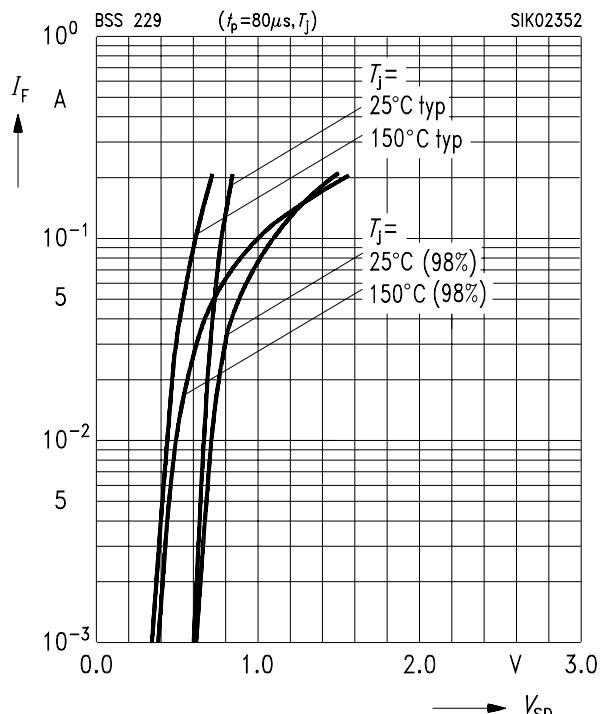
Typ. capacitances $C = f(V_{DS})$
 parameter: $V_{GS} = 0$, $f = 1$ MHz



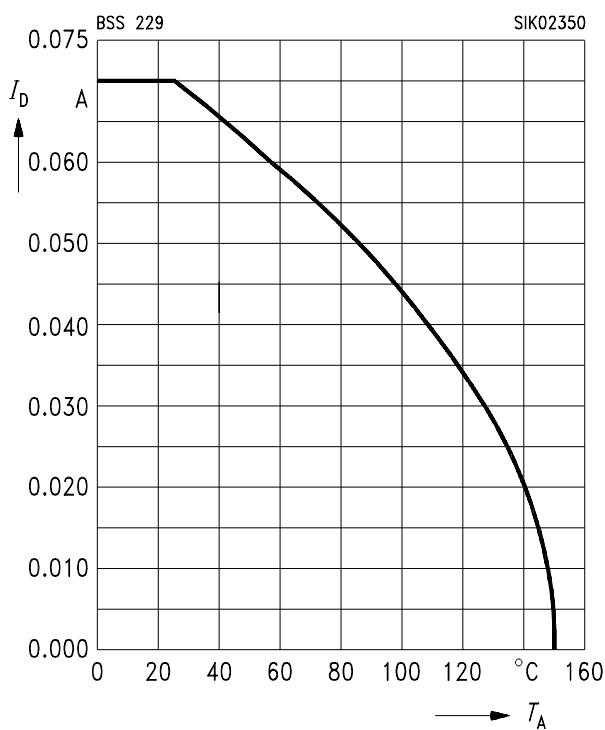
Gate threshold voltage $V_{GS(th)} = f(T_j)$
 parameter: $V_{DS} = 3 \text{ V}$, $I_D = 1 \text{ mA}$, (spread)



Forward characteristics of reverse diode
 $I_F = f(V_{SD})$
 parameter: $t_p = 80 \mu\text{s}$, T_j , (spread)



Drain current $I_D = f(T_A)$
 parameter: $V_{GS} \geq 3 \text{ V}$



Drain-source breakdown voltage
 $V_{(BR)DSS} = b \times V_{(BR)DSS} (25^\circ\text{C})$

